## **AMENDMENTS TO THE ABSTRACT**

Please substitute the following paragraph for the abstract now appearing in the currently filed specification:

The present invention relates to an<u>An</u> integrated circuit arrangement (1) comprising including a nonplanar substrate (2) on which an integrated circuit is formed on at least one side, wherein thea side (3) of the substrate (2) which has the integrated circuit being is arranged on a carrier (4) and the carrier (4) being is produced from a chemically resistant material.